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ON Semiconductor®

FDD86569-F085

N-Channel PowerTrench[®] MOSFET 60 V, 90 A, 5.7 m Ω

Features

- Typical $R_{DS(on)}$ = 4.2 $m\Omega$ at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{g(tot)}$ = 35 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- PowerTrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems



Symbol	rameter	Ratings	Units
V_{DSS}	Drain-to-Sr , ce Voltage	60	V
V_{GS}	Gate-to-Sc ce Volta >	±20	V
1	r uin currei Con⁴ uous (V _{GS} = (2) (Note 1) T _C = 25°C	90	A
ID	n Current 7 _C = 25°C	See Figure 4	^
FAG	Single Pi : Avalanche E nergy (Note 2)	41	mJ
ID T	'owe, Dissipation	150	W
P_D	L _rate Abo re 25,0C	1.0	W/°C
T _J , T _G	Operating and Storage Temperature	-55 to + 175	°C
, ic	Thermal Resistance, Junction to Case	1.0	°C/W
$R_{\theta J \Lambda}$	Maximum 1 Fermal Resistance, Junction to Ambient (Note 3)	52	°C/W

Notes:

- 1: Current is limited by 50 no vire configuration.
- 2: Starting T_J = 25°C, L = ¬□µH, I_{AS} = 74A, V_{DD} = 60V during inductor charging and V_{DD} = 0V during time in avalanche.

 3: R_{θ,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder
- 3: R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design, while R_{0JA} determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD86569	FDD86569-F085	D-PAK(TO-252)	13"	16mm	2500units

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Publication Order Number: FDD86569-F085/D

Units

Max.

Ele	ctrical	Characteristics	T _J = 25°C unl	ess otherwise noted.
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Parameter

Off Characteristics							
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$,	V _{GS} = 0V	60	-	-	V
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} =60V,	$T_J = 25^{\circ}C$	-	-	1	μΑ
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA
loce	Gate-to-Source Leakage Current	$V_{00} = +20V_{00}$	1	_	_	+100	nΑ

Test Conditions

Min.

Тур.

On Characteristics

Symbol

١	V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{I}$	_D = 250μA	2	2.5		V
	R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	4.	5.,	mΩ
			V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$		8.3	11	mΩ

Dynamic Characteristics

		A
Input Capacitance	2520 -	pF
Output Capacitance		pF
Reverse Transfer Capacitance	1 - 11/11/2	pF
Gate Resistance	V _{GS} = 0.5V, -1N 7 - 2.0 -	Q
Total Gate Charge	V_C 1 to 10 V_C = 30 V_C - 35 52	UC.
Threshold Gate Charge	V _{GS} = 72V I _D = 85A - 73	nC
Gate-to-Source Gate Charge	- 14	nC
Gate-to-Drain "Miller" Charge	N 2 - 3 N -	nC
	Output Capacitance Reverse Transfer Capacitance Gate Resistance Total Gate Charge Threshold Gate Charge Gate-to-Source Gate Charge	Output Capacitance $V_{DS} = 30V$, $V_{GS} = 0V$, $f = 1MHz$ Gate Resistance $V_{GS} = 0.7V$, $11V_{CS} = 2.0$ Total Gate Charge $V_{CS} = 0.7V$, $11V_{CS} = 30V$, $11V_{C$

Switching Characteristic

t _{on}	Turn-On Tir	-	-	53	ns
t _{d(on)}	Turn-On [lay	-	15	1	ns
t _r	$V_{DD} = 30 \text{ V, } I_D = 80 \text{A,}$	-	20	1	ns
$t_{d(off)}$	$urn-O#Peic$ = 10V, $R_{GEN} = 6\Omega$	-	22	-	ns
t _f	I TIME	-	8	-	ns
	Tu of .ime	-	-	45	ns

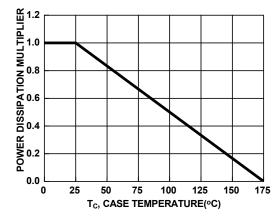
Drai. So. ce Dicge Characterisacs

	Source-to-Drain Dioge Voltage	$I_{SD} = 80A, V_{GS} = 0V$	-	-	1.25	V
טרי	Sculpe-to-17.4.11 Diode Vol(at)=	$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	V
t _{r:}	Reverse-Recovery (ir te	V _{DD} = 48V, I _F = 80A,	-	52	68	ns
\mathcal{O}^{LL}	Reverse-Recovery Charge	$dI_{SD}/dt = 100A/\mu s$	-	43	65	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



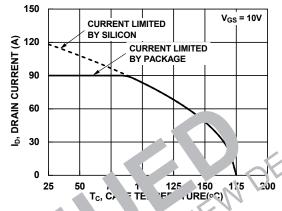


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. axi. m Co tinuous Diain Current vs.

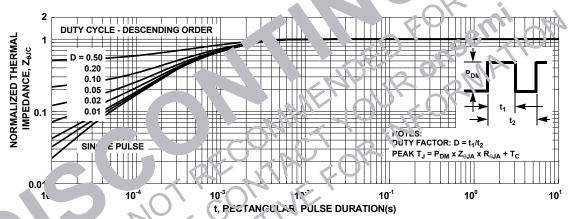


Figure 3. Normalized Maximum Transient Thermal Impedance

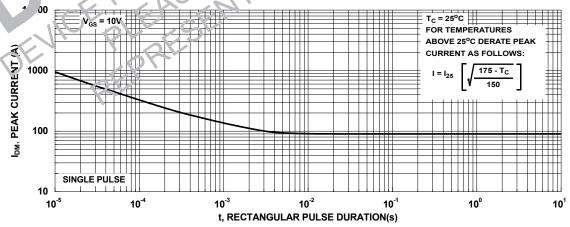


Figure 4. Peak Current Capability

Typical Characteristics

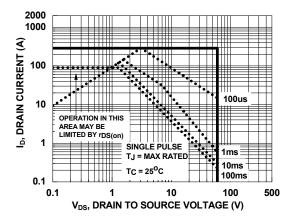
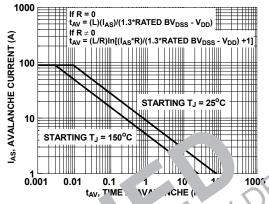
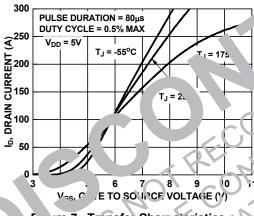


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Sem. nduc Applir on Note: AN75 \downarrow 4 and AN7515

Figure Un ampe Inductive Switching



F. re 7. Transfer Characteristics

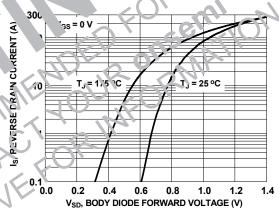


Figure 8. Forward Diode Characteristics

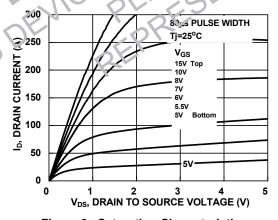


Figure 9. Saturation Characteristics

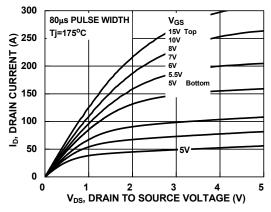


Figure 10. Saturation Characteristics

Typical Characteristics

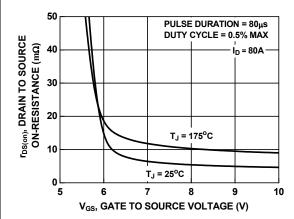


Figure 11. R_{DSON} vs. Gate Voltage

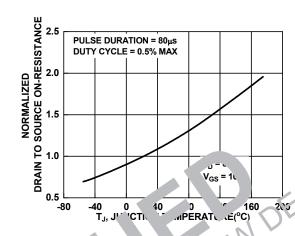
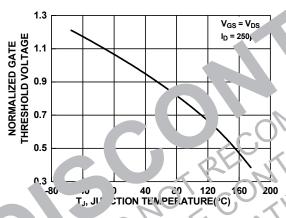


Figure 12 Norma rea SON vs. Junction Ten grature



Figu 15 lormalized Gate Threshold Voltage vs.

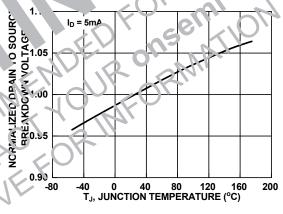


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

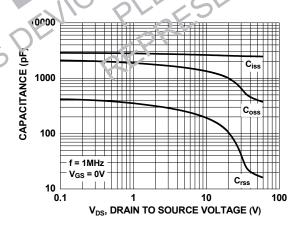


Figure 15. Capacitance vs. Drain to Source Voltage

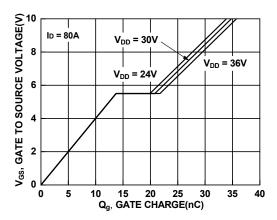


Figure 16. Gate Charge vs. Gate to Source Voltage



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